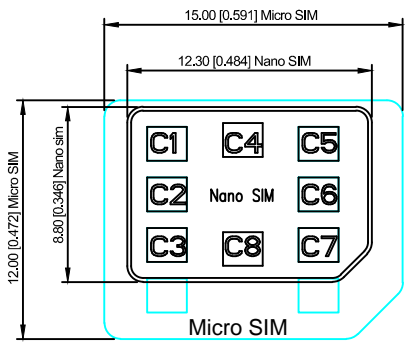
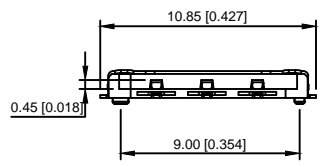
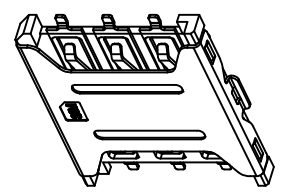


RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)



Specification

材料 MATERIAL:
 绝缘材料 Insulator: High Temperature Thermoplastic, UL 94V-0.
 触点 Contact:C5210
 外壳 SHELL:SUS

电镀 PLATING:
 触点 Contact:Plated 50u"Ni Overall Contact ALL Au 1U,
 外壳 Shell:Plated 50u"Ni Overall,PAD Au 1U

电气 Electrical:
 额定电流 Current Rating :0.5mA AC/DC max.
 额定电压 Voltage Rating :125V AC/DC
 环境温度 Ambient Temperature Range :-20°C+60°C
 储存温度 Storage Temperature Range :-40°C+70°C
 环境湿度 Ambient Humidity Range :95% R.H. Max.
 接触电阻 Contact Resistance:100mΩ max.
 绝缘电阻 Insulation Resistance:1000MΩmin./500VDC
 无通电寿命 Mating Cycles:10,000 Insertions
 回流峰值温度 Reflow peak temp.:260°C ±5°C, 3~5 S
 通电寿命 Mating Cycles:3,000 Insertions Min

XKB Connectivity

| SIM pin assignment | |
|--------------------|---------|
| PIN# | Name |
| C1 | VCC供电电压 |
| C2 | RST重置 |
| C3 | CLK时钟 |
| C5 | GND接地 |
| C6 | VPP程序电压 |
| C7 | I/O输入输出 |

| | | | | | |
|---------------------------------------|---|------|---------|------------------------|------------------------------|
| DSND | | DATE | | SCALE: N/A | MODEL TYPE: SIM CARD CONN |
| ΔX | | DATE | | VIEW: | PART NO.: |
| ΔX | | DATE | | UNIT: mm/in | DWG NO.: |
| ΔX | | DATE | | SIZE: A4 | XKNANO-1151 |
| MARK | DESCRIPTION | DATE | REVISED | APPROVED | WEIGHT |
| | REVISIONS | | | UNSPECIFIED TOLERANCES | SHEET |
| | www.xk-dg.cn www.helloxkb.com www.helloxkb.cn | | | | REVISION |
| XKB INDUSTRIAL PRECISION CO., LIMITED | | | | | 1.0g |
| | | | | | 1/1 |
| | | | | | A0 |